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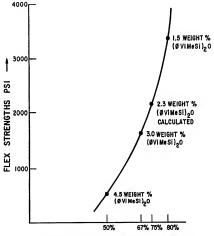
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- (54) Curable solventiess organopolysiloxane compositions
  - (57) A reactive diluent of the formula:
- $[CH_2 = CH(CH_3)_2SiO]_2Si(C_6H_5)2$

is added to an organopolysiloxane composition in which the organopolysiloxane has at least 8 Si atoms and 67 to 85 mol % C<sub>8</sub>H<sub>8</sub>SiO<sub>3/2</sub> and 33 to 15 mol %

 $CH_2 = CH(CH_3)_2SiO_{1/2}$ 

units, containing both platinum catalyst and a silicon hydride crosslinker, so as to give good handling properties combined with valuable mechanical properties. EFFECT OF VARYING AMOUNTS OF (ØVIMeSi)<sub>2</sub>O FLUID IN THE RESIN.



% BASE RESIN / REMAINDER (Ø ViMeSi)<sub>2</sub>O IN PART TWO

FIG. I

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# SPECIFICATION

# Curable solventless organopolysiloxane compositions

5 The present invention relates to curable organopolysiloxane resins containing a reactive diluent. Organopolysiloxane resins in which the substituent organic groups are methyl, phenyl, vinyl and/or similar organic groups are well-known. These materials cure through a variety of mechanisms, such as peroxide catalysed vinyl groups on sillcon ro by the platinum catalysed addition of silicon hydride to alkenyl groups on silicon. The properties of these organopolysilox-

10 ane resins such as toughness and retention of strength at high temperatures make them useful in casting resin applications.

The resins that are useful for casting applications are those that have relatively high viscosities, of the order of 5.0 5.0 200 Pas or higher. These resine, even though they have the desired strengths, have one important disedvantage. Because of their high viscosities, they are 15 extremely difficult to handle in use. They do not pour rapidly and have slow flow when cast into 15

place.

The problem is, therefore, posed as to how one can use the high viscosity resins for their desirable properties and at the same time obtain desirable handling properties.

An obvious solution is to dilute the resins with solvent but this approach leads to bubble 20 entrapment when the casing resin is heated to cure it. It also leads to the time-consumling step 20 of solvent removal from the cast resin.

Most recent attempts to solve the handling problem have been to incorporate a low molecular weight cross-linker in the system. For example, Clark in U.S. Patent 2,894,930 shows a onepart, curable casting resin wherein he suggests using

$$(CH_2 = CH(CH_3)_2Sio)_2Si(C_6H_8)_2$$

as a portion of the reactive alkonyl-containing resin. The materials are cured through the use of peroxidic catalysts. These materials have the advantage of being one-part, that is, all the 30 essential ingredients can be mixed together and stored without the material curing. The disadvantage, of course, is the fact that the peroxide-cured, one-part materials require a long

period of time to cure.

Mink et al., in U.S. Petent 3,944,519, overcomes the letter problem by increasing the rate of cure of such resins by changing the cure system from the peroxide-cured vinyl to the platinum

40 Thus, Mink et al. utilized low molecular weight (low viscosity) silicon hydride cross-linker organopolysiloxanes in a vinyt-containing organopolysiloxane to enhance the cure rate and also to reduce the viscosity of the vinyisiloxane resin so that it could be easily handled. The patent teaches that only specific silicon hydride containing crosslinkers work. The use of low molecular weight vinyi-containing dilutents is not shown or suggested therein.

45 We have now found that by adding a specific low molecular weight vinyl-containing diluent, 45 lower viscosities of the casting resins can be obtained without sacrificing the desirable

mechanical properties of the higher viscosity casting resin.

35 catalysis of the silicon hydride addition to alkenyl groups i.e:

This invention consists in an improved curable composition consisting essentially of a mixture of (a) an organopolysiloxane containing from 87 to 85 mol percent C<sub>2</sub>H<sub>2</sub>SiO<sub>2/2</sub> units and 33 to 50 15 mol percent of CH<sub>2</sub> – CH(CH<sub>2</sub>)<sub>2</sub>SiO<sub>2/2</sub> units, said organopolysiloxane having an average of at least 8 silicon atoms per molecule; (b) a silcon hydride containing polysiloxane crosslinker for (a), said component (b) being present in an amount sufficient to provide from 0.9 to 1.1 mol of silcon hydride per mol of CH<sub>2</sub> – CHSi present in (a) and (d); (d) a platinum catalyst in an amount sufficient to catalyse the reaction of the silcon hydride with the CH<sub>2</sub> – CHSi; - and (d) a reactive

55 diluent having the formula:

$$[CH2 = CH(CH3)2SiO]2Si(C6H5)2.$$

In the composition, the organopolysiloxane resin (a) the base resin. The feature of resin (a) is 60 that it has a sufficiently high viscosity to give the desired mechanical strength to the cured composition. The resin (a) is essentially the same as that described in Mink et al., discussed above, and consists of monophenylsiloxy units in the range of from 67 to 85 mol percent; and dimethylvinysiloxy units in the corresponding range from 33 to 15 mol percent. It is preferred that the resin (a) should have 75 mol percent of monophenylsiloxy units and 25 mol percent of 65 the dimethylvinysiloxy units.

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The resin is easily prepared by conventional hydrolysis of the corresponding chloro- or alkoxysilanes and conventional condensation techniques. Although there does not appear to be any upper limit on the molecular weight of the resin (a), it should have a degree of polymerization of at least 8 silcon atoms per molecule. This is to ensure adequate physical 5 strengths in the final product. The resin (a) can also be treated, for example, by alkaline 5 condensation catalysts, to reduce the silanol content of the resin. The silicon hydride containing the siloxane (b) serves as a crosslinker and curing agent in the cureble composition. This materiel can be any silcon hydride containing silane or siloxane that is compatible and gives the cured composition the desired properties. The material may be, 10 for example, the polymer found in the Mink et al. U.S. Patent at column 2, lines 23-25 or [H(CH<sub>2</sub>)<sub>2</sub>SiO]<sub>2</sub>Si(C<sub>6</sub>H<sub>6</sub>)<sub>2</sub> or [H(CH<sub>2</sub>)<sub>2</sub>SiO]<sub>2</sub>SiC<sub>6</sub>H<sub>6</sub>. The crosslinker must have at least two (2) silicon hydrogens per molecule. There must be 15 enough of component (b) present to give from 0.9 to 1.1 mol of silicon hydride per mol of 15 alkenyl groups in the curable composition. Preferred a ratio of 1 mol of silicon hydride to 1 mol of alkenyl is preferred for the best results. The crosslinker (b) can be prepared by conventional techniques known to those skilled in the art, for example, the cohydrolysis of the corresponding The platinum catalyst (c) can be any of the well-known forms of catalytic platinum, ranging 20 from finely divided platinum metal to platinum on various carriers to the chloroplatinic acid and complexed platinum compounds. Chloroplatinic ecid in a small amount of solvent or [(R<sub>3</sub>P)<sub>2</sub>PtCl]<sub>2</sub> where R is methyl, ethyl, propyl or butyl is preferred. There should be et least 0.1 part by weight of platinum per million parts by weight of the 25 combined total of components (a), (b) and (d) end 1-20 parts pt per million parts are preferred. 25 The unique component of this invention is the component (d), the vinyl containing siloxane  $[CH_2 = CH(CH_3)_2SiO]_2Si(C_6H_6)_2$ 30 On mixing the diluent (d) with the component (a) in a ratio of (d) to (a) of from 20/80 to 50/ 50, a solventless material is produced which has a maximum viscosity of about 2.5 Pars. The preferred ratio is 25 parts of (d) to 75 parts of (e). This specific material is the only one of many similar materials that was effective in this invention. [CH2 = CH(CH3)2Si]2O was too voletile while 35  $[(C_6H_6) (CH_3)(CH_2 = CH)Si]_2O$  and  $[CH_2 = CH(CH_3)_2SiO]_2SiCH_3(C_6H_6)$ , although non-volatile, reduced the mechanical properties of the cured resin. This meterial is eesily prepered by the same methods as indicated for the component (b) above. Generally, for e two-component system, the component (d) is mixed into one peckage with a smell portion of the base resin (a) end the catalyst required for cure. The remainder of the bese resin (a) and the crosslinker (b) are mixed together to form a second package. The means for and manner of mixing these individual materials are not critical provided the mixtures are rendered homogenous. The two packages can then by mixed together et the eppropriate time 45 for their use and cast into place. Upon heating, the composition cures. If other materials ere to be mixed with the composition, they should be incorporated in to the individual packages during their preparation rather than adding those materials at the final mixing of the whole composition. Other materials that cen be incorporated in the resin composition of this invention are conventionel fillers such as glass fibers, finely divided silice, crushed quartz, powdered glass, 50 asbestos talc, carbon black, iron oxide, titanium oxide, megnesium oxide or mixtures thereof. 50 Also included ere pigments, dyes, oxidation inhibitors, cure inhibitors and release agents. The curable composition can be employed in any conventional manner for casting or impreaneting. The components (a), (b), (c) and (d) are mixed together with any of the above desired 55 additives and mixed to homogeneity. The mixture is then fabricated into the desired form and cured, usually at elevated temperatures, for example, 100-150°C. It may be desirable in some cases to post-cure the cured meterial et eleveted temperatures, for exemple, up to 200°C. The accompanying drawing shows the effect of varying amounts of (&ViMeSi)<sub>2</sub>O fluid in the resin. The drawing is e graph illustrating verietion in flux strengths (PSI) as a function of % base 60 60 resin/remeinder (φViMeSi), O in part two. The following examples are by way of comparison with the systems currently in the prior art. The examples ere not intended as limiting the invention delineated in the cleims.

A bese resin was prepared consisting of 75 mol percent of monophenylsiloxy units and 25

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Example 1

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mol percent of vinyldimethylsiloxy units and was designeted "A". Various types of crosslinkers designated "B", "C" end "D" respectively were prepared and mixed with A according to conventional techniques in the amounts shown in Table I below. The mixture of B with A is the example of the prior art shown in Mink et al., U.S. Patent No. 3,944,519 at Table II, middle 5 column. Component B is IHICHJ.SiOI.SiCHJ.Si Component C is

[H(CH<sub>3</sub>)<sub>2</sub>SiO]<sub>3</sub>SiC<sub>8</sub>H<sub>6</sub>

end component D is 35 mole percent of diphenylsiloxy units 55 mole % of HCH,SiO units and 10 10 mole percent of (CH,),SiO, units. The catalyst was 1% [(C,H,),P],pCI, in toluene. Runs 1, 1 2 and 3 are outside the scope of the invention end represent the prior ert.

Runs 4, 5 and 6 illustrete the invention and show the effect of the eddition of component (d): (CH<sub>2</sub> = CH(CH<sub>3</sub>),Si(C<sub>3</sub>H<sub>3</sub>). Two-part compositions were prepared wherein part one was the base resin (a) and the crosslinker (b) and the second part was the component (d) and the catalyst 15 and a small amount of component (a) as e carrier. The ratio of part one to part two was 10:1.

5 and a small amount of component (a) as e carrier. The ratio of part one to part two was 10:1.

The results ere shown in Table II below.

The results ere shown in Table it belo

#### Example 2

This example serves to illustrate the comparison between the prior art diluent (\$VIMeSi)<sub>2</sub>O and 20 the present diluent. As the amount of the prior art diluent is increased, the flex strength of the resulting resin is reduced. The increase in diluent is to decreese the viscosity so that the base resin can be easily hendled

Runs 7, 8 and 9 in Table 3 below show the use of (\$\forall ViMeSi)\_0 as the reactive dilluent, wherein \$\phi\$ is \$\mathbb{C}\_H^1\_-\$. Vi is \$\mathbb{C}\_H^1\_-\$ and \$Me is \$\mathbb{C}\_H^1\_-\$. Two-part compositions were again 25 prepared wherein part one was the base resin (a) and the second part was (\$\sim MiMSi)\_0\$, the catelyst and a small amount of component (a) as e carrier. The ratio of part one to part two was 10:1. The catalyst was the same as used in Example 1.

# TABLE I

30	Run No.	Parts A	Parts B	Parts C	Parts D	ppm cat
	1	74.3	25.7			10
35	2	81.4		18.6		10
	3	70			30	10

# TABLE I CONTINUED

40	Run No.	Visc Pa·s At 25°C uncured	Cured flex Strength psi	Cured ten modulus psi × 10 <sup>5</sup>	Cured sec modulus psi × 10 <sup>5</sup>	Ratio ten/ sec
45	1 2 3	3.0 3.0 >40.0	5500 7500 7500	1.25 1.40 1.54	0.163 0.50 0.85	7.67 2.80 1.81

### TABLE II

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55	Run No.	Total Parts A	Total Parts B	Total Parts C	Total Parts D	perts Component (d)	Cat ppm	
	4	78.3	29.2			2.5	10	
	5	86.2		21.3		2.5	10	
	6	74			33.5	2.5	10	

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TABL	E II	CONTIL	NUED

5	Viscosity Pa·s at 25°C of pert one.	Cured flex Strength psi	Cured ten Modulus psi × 10 <sup>5</sup>	Cured sec modulus psi × 10 <sup>5</sup>	Retio ten/ sec
	5.0	3255	0.933	0.128 0.428	7.29 2.97
10	2.0	6133			1.69
	5.0	7543	1.72	1.01	1.69

TABLE III

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	Run No.	Total Perts A	Total Parts B	Total Parts (φViMeSi) ₂0	Cat ppm	Pa·s Viscosity of part one at 25C.
!0	7	79.2	29.2	1.67	10	3.3
	8	76.6	30.2	3.33	10	2.1
	9	74.0	31.0	5.00	10	weter thin

TABLE III CONTINUED

30	Run No.	Pa·s Viscosity of all Components at 25C	Cured Flex Strength psi	Cured ten Modulus psi × 10 <sup>5</sup>	Cured sec Modulus psi × 10 <sup>5</sup>	Ratio tan/ sec
	7	17.8*	3434	.796	.128 .129	6.2 2.00
35	9	.48 water thin	1667 549	.259 .042	.129	

<sup>\*</sup> Unacceptable For Handling.

1. An improved curable composition consisting essentially of a mixture of

(e) an organopolysiloxane conteining from 67 to 85 mol percent C<sub>8</sub>H<sub>5</sub>SiO<sub>3/2</sub> units and 33 to 15 mol per cent of CH<sub>2</sub> = CH(CH<sub>3</sub>)<sub>2</sub>SiO<sub>1/2</sub> units, said organopolysiloxane having an everage of at leest 8 silicon etoms per molecule;

45 (b) e silicon hydride-conteining polysiloxane crosslinker for (e), the component (b) being present in en emount sufficient to provide about 0.9 to 1.1 mol of silicon hydride per mol of CH2 = CHSi = present in (a) end (d);

(c) a platinum cetalyst in an amount sufficient to catalyse the reaction of the silicon hydride with the CH<sub>2</sub> = CHSi-: end
(d) a reactive diluent heving the formule  $[CH_2 = CH(CH_a)_2SiO]_aSi(C_aH_a)_a$ .

2. A curable composition es claimed in cleim 1, wherein the pletinum cetalyst (c) is present

in an amount sufficient to provide at least 0.1 pert by weight pletinum per million parts of the combined weight of (a), (b) end (d).

- 3. A curable composition as claimed in claim 1 or 2 wherein the component (b) is present in 55 an emount sufficient to provide substentially 1.0 mol of silicon hydride per mol of CH, = CHSi-55 in (a) and (d).
  - 4. A curable composition as claimed in any of claims 1 to 3 wherein the component (d) is present in an amount of from 20 to 50 parts by weight corresponding of from 80 to 50 parts by weight of the component (a).
- 60 5. A curable composition as claimed in claim 4 wherein the amount of (d) present is 25 parts by weight and there are present 75 parts by weight of (a).
  - 6. A curable composition as claimed in claim 1 substantially as here described with reference to any of the specific examples.

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